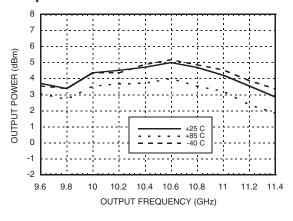


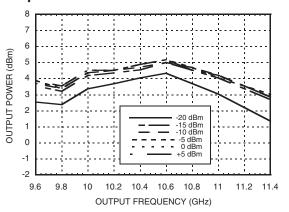


SMT GaAs HBT MMIC x4 ACTIVE FREQUENCY MULTIPLIER, 9.8 - 11.2 GHz OUTPUT

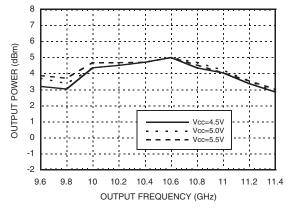
Output Power vs. Temperature @ -10 dBm Drive Level



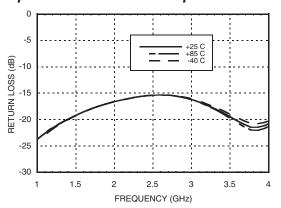
Output Power vs. Drive Level



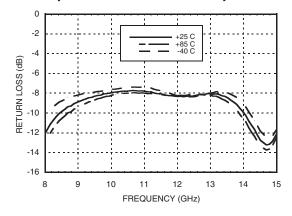
Output Power vs. Supply Voltage @ -10 dBm Drive Level



Input Return Loss vs. Temperature



Output Return Loss vs. Temperature



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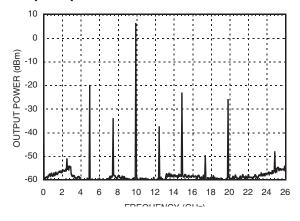
HMC443LP4 / 443LP4E

v04.0210

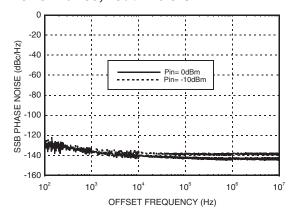


SMT GaAs HBT MMIC x4 ACTIVE FREQUENCY MULTIPLIER, 9.8 - 11.2 GHz OUTPUT

Output Spectrum



SSB Phase Noise Performance, Fout= 10.5 GHz



HMC443LP4 / 443LP4E

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SMT GaAs HBT MMIC x4 ACTIVE FREQUENCY MULTIPLIER, 9.8 - 11.2 GHz OUTPUT

Absolute Maximum Ratings

RF Input (Vcc = +5V)	+20 dBm
Vcc	+5.5V
Channel Temperature	135 °C
Continuous Pdiss (T=85 °C) (derate 7.6 mW/°C above 85 °C)	500 mW
Thermal Resistance (R _{th}) (junction to ground paddle)	130.8 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C

Typical Supply Current vs. Vcc

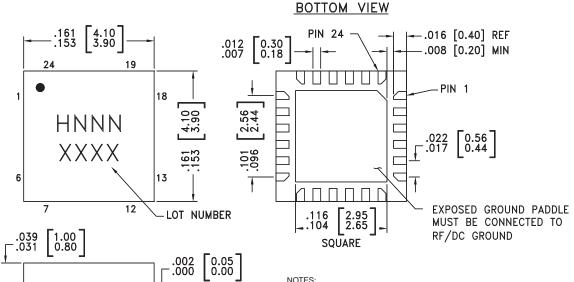
Vcc (V)	Icc (mA)
4.5	51
5.0	52
5.5	54

Note: Multiplier will operate over full voltage range shown above.



ELECTROSTATIC SENSITIVE DEVICE **OBSERVE HANDLING PRECAUTIONS**

Outline Drawing



SEATING

PLANE

-C-

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

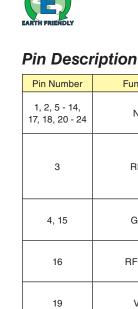
.003[0.08] c

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC443LP4	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H443 XXXX
HMC443LP4E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H443 XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX

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SMT GaAs HBT MMIC x4 ACTIVE FREQUENCY MULTIPLIER, 9.8 - 11.2 GHz OUTPUT

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Pin Number	Function	Description	Interface Schematic
1, 2, 5 - 14, 17, 18, 20 - 24	N/C	The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
3	RFIN	RF input needs to be DC blocked only if there is an external DC voltage applied to RF IN.	RFIN ○
4, 15	GND	All ground leads and ground paddle must be soldered to PCB RF/DC ground.	○ GND =
16	RFOUT	Multiplied Output. AC coupled. No external DC blocks necessary.	— —○ RFOUT
19	Vcc	Supply voltage 5V ± 0.5V.	

ANALOGDEVICES

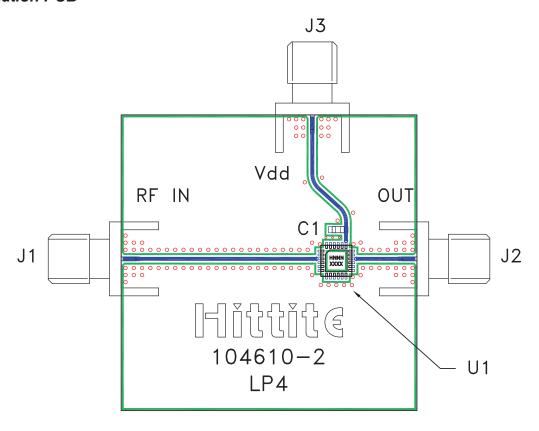
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SMT GaAs HBT MMIC x4 ACTIVE FREQUENCY MULTIPLIER, 9.8 - 11.2 GHz OUTPUT

Evaluation PCB



List of Materials for Evaluation PCB 106137 [1]

Item	Description
J1 - J3	PCB Mount SMA Connector
C1	1,000 pF Capacitor, 0603 Pkg.
U1	HMC443LP4 / HMC443LP4E x4 Active Multiplier
PCB [2]	104610 Eval Board

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350